InfinityLine V+

Vertical Touch-Free Wet Processing for Next-Generation Substrates.

The InfinityLine V+ introduces a new era of vertical, touch-free wet processing for advanced HDI and IC substrate production. Using it enables gentle, uniform, and contamination-free handling of even the thinnest substrates.
A modular system architecture, cleanroom-ready design, and full Industrie 4.0 connectivity ensure
maximum flexibility, scalability, and production reliability for future-oriented processes such as SAP and mSAP.

- Photoresist Develop
- Soldermask Develop
- Dryfilm Strip
- Cu-Flash-Etch
- Ti-Flash-Etch
- Cleaning
- Surface Treatment
- MEC (OAP)

Key Performance Indicators

Panel Size	Maximum 623 mm x 623 mm
Panel Thickness	35µm CCL / 200µm glass Maximum 2.40 mm

Panel Weight	Maximum 2.4 kg
Capabilitiy	Development with Resist Thickness 5µm down to L/S 2µm Flash Etch with Cu Thickness 1µm - 2µm down to L/S 3µm

Other dimensions on demand

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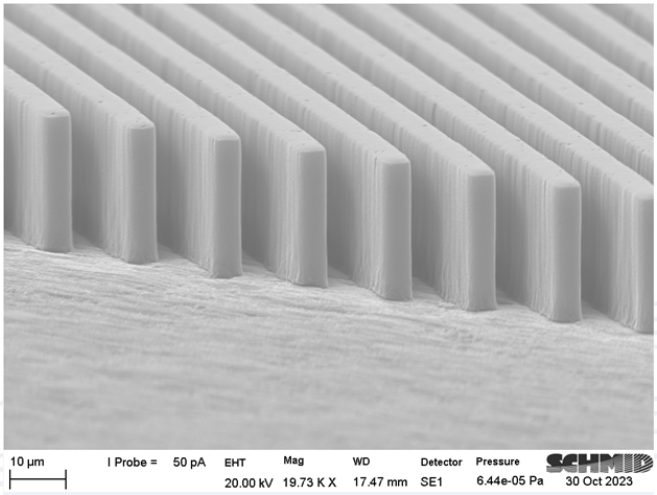
Process Highlights

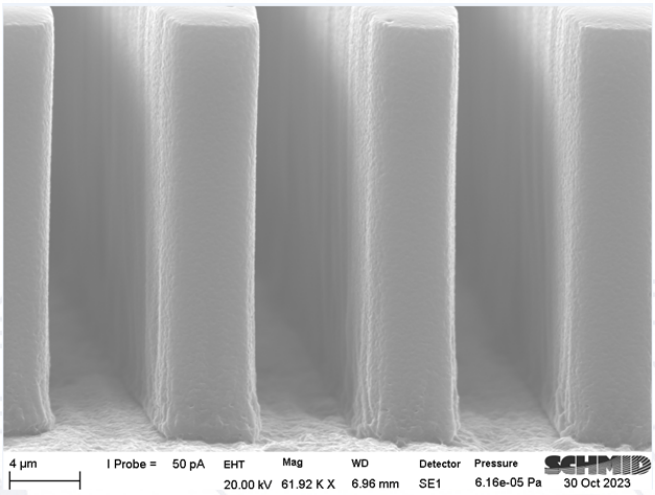
High-performance vertical wet processing for advanced SAP and mSAP production.

Combining maximum throughput, superior uniformity, and Industry 4.0 readiness in one modular system.

- Vertical inline concept for highest panel throughput per hour
- Excellent process uniformity across the full panel
- SCHMID's innovative clamping frame technology
- Low chemical and energy consumption - reduced TCO
- Compact, cleanroom-ready design
- Digital process control with SECS/GEM integration
- Flexible configuration for various substrates and automation levels

Process Results - SEM





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